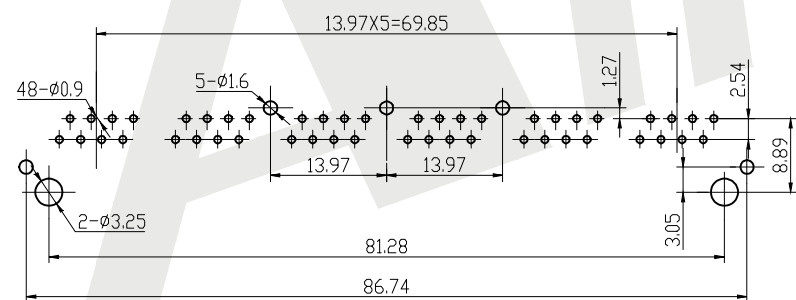
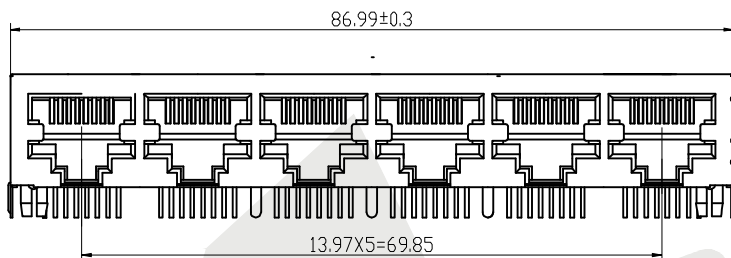
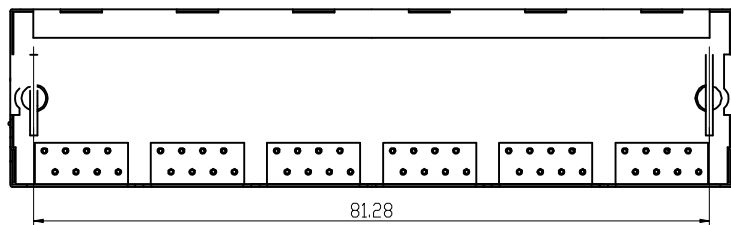


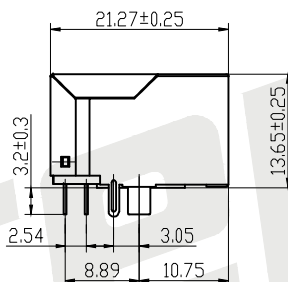
HSF



ROHS



PC Board Layout



NOTES:

MATERIAL:

- HOUSING MATERIAL:GLASS FILLED POYESTER UL94V-0.
 - CONTACT MATERIAL:PHOSPHOR BRONZE $t=0.3\text{mm}$
 - PLATING:SELECTING GOLD PLATING $1\mu\sim 50\mu$ "OVER NICKEL IN CONTACT AREA. 150μ " TIN PLATIN. OVER NICKEL IN SOLDER AREA
 - SHIELD:0.2mmTHICKNESS COPPER WITH NICKEL PLATEI
- ELECTRICAL
- VOLTAGE RATING:125V AC RMS
 - CURRENT RATING:1.5AMP
 - CONTACT RESISTANCE:30 MILLIOHMS MAX
 - INSULATION RESISTANCE 500 MEGOHMS MIN @500V DC
 - DIELECTRIC WITHSTANDING RESISTANCE :1000V AC RMS 50Hz. 1MIN

MECHANICAL

- DURRABILITY:750 CYCLES MIN
- PCB RETENTTON PRB-SOLDER:1 LB MIN

REVIORNMENTAL

- STORAGE:-40° C TO 85° C
- OPERATION:0° C TO 70° C

Order code:

ATRJ5921 - 10P - 8C - X - D - E - D

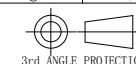
- | | | | | | | |
|--------------|---|--|---|---|--|---|
| ① | ② | ③ | ④ | ⑤ | ⑥ | ⑦ |
| ① SERIES NO: | ② NUMBER OF POSITIONS (10P, 8P, 6P, 4P) | ③ NUMBER OF CONTACTS (10C, 8C, 6C, 4C) | ④ Contact Plating | ⑤ Shield | ⑥ Ports | ⑦ PCB layout style: |
| | | | G0:G0ld flash
G1: 3U" Gold
G2: 5U" Gold
G3:10U" Gold
G4:15U" Gold
G5:30U" Gold
SN:Tin | A:W/O Shield
B:Half Shield
C:Shield W/Eml
D:Shield W/O Eml | A:1X1P G:2X1P
B:1X2P H:2X2P
C:1X4P I:2X3P
D:1X5P J:2X4P
E:1X6P K:2X6P
F:1X8P L:2X8P | A:TYPE 1 front legs 3.05
B:TYPE 1 front legs 3.68
C:TYPE 1 front legs 4.57
D:TYPE 2 Back legs 3.05
E:TYPE 2 Back legs 3.68
F:TYPE 2 Back legs 4.57 |

Unless Otherwise specified tolerance
 X. ±0.35 X.XX: ±0.20
 X.X: ±0.25 X.XXX: ±0.15

Antenk® ANTENK ELECTRONICS CO.,LTD
[Http://www.antenk.com](http://www.antenk.com)
 E-mail:sales@antenk.com

SCALE: As Shown	UNIT: mm
DRAW Wu Feng Rong	DATE 22/03/2018
CHECK BobYang	DATE 22/03/2018

TITLE:
RJ45 JACK Side entry, shielded,
1X1P Back 3.05



DRAWING NO: ATRJ5921-10P8C-X-D-E-D
 PRODUCT NO: ATRJ5921-10P8C-X-D-E-D

REV	DESCRIPTION	DATE
1		
2		
3		
4		
5		